

MC14007UB

Dual Complementary Pair Plus Inverter

The MC14007UB multi-purpose device consists of three N-channel and three P-channel enhancement mode devices packaged to provide access to each device. These versatile parts are useful in inverter circuits, pulse-shapers, linear amplifiers, high input impedance amplifiers, threshold detectors, transmission gating, and functional gating.

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range
- Pin-for-Pin Replacement for CD4007A or CD4007UB
- This device has 2 outputs without ESD Protection. Anti-static precautions must be taken.

MAXIMUM RATINGS (Voltages Referenced to V_{SS}) (Note 2.)

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V_{in}, V_{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to $V_{DD} + 0.5$	V
I_{in}, I_{out}	Input or Output Current (DC or Transient) per Pin	± 10	mA
P_D	Power Dissipation, per Package (Note 3.)	500	mW
T_A	Ambient Temperature Range	-55 to +125	°C
T_{stg}	Storage Temperature Range	-65 to +150	°C
T_L	Lead Temperature (8-Second Soldering)	260	°C

2. Maximum Ratings are those values beyond which damage to the device may occur.

3. Temperature Derating:
Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

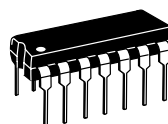
Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



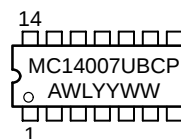
ON Semiconductor

<http://onsemi.com>

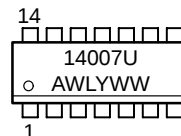
MARKING DIAGRAMS



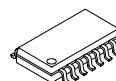
PDIP-14
P SUFFIX
CASE 646



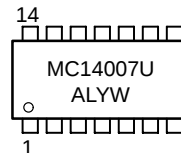
SOIC-14
D SUFFIX
CASE 751A



TSSOP-14
DT SUFFIX
CASE 948G



SOEIAJ-14
F SUFFIX
CASE 965



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

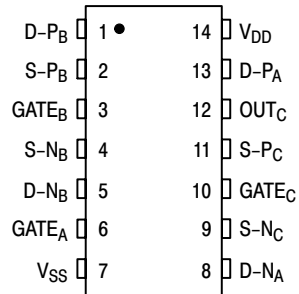
ORDERING INFORMATION

Device	Package	Shipping
MC14007UBCP	PDIP-14	2000/Box
MC14007UBD	SOIC-14	55/Rail
MC14007UBDR2	SOIC-14	2500/Tape & Reel
MC14007UBDT	TSSOP-14	96/Rail
MC14007UBF	SOEIAJ-14	See Note 1.
MC14007UBFEL	SOEIAJ-14	See Note 1.

1. For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

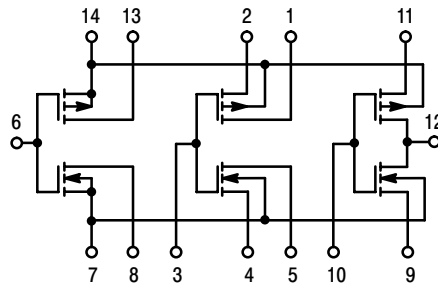
MC14007UB

PIN ASSIGNMENT

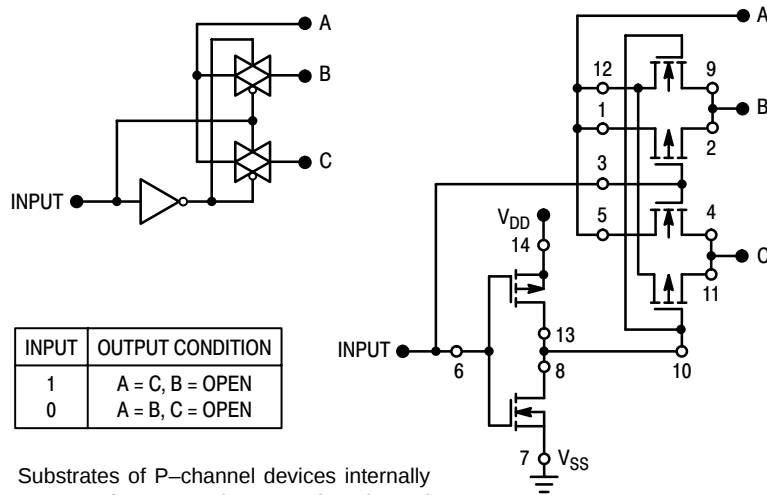


D = DRAIN
S = SOURCE

SCHEMATIC



V_{DD} = PIN 14
V_{SS} = PIN 7



Substrates of P-channel devices internally connected to V_{DD}; substrates of N-channel devices internally connected to V_{SS}.

Figure 1. Typical Application: 2-Input Analog Multiplexer

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ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V _{DD} Vdc	– 55°C		25°C			125°C		Unit
			Min	Max	Min	Typ (4.)	Max	Min	Max	
Output Voltage V _{in} = V _{DD} or 0	V _{OL}	5.0	—	0.05	—	0	0.05	—	0.05	Vdc
		10	—	0.05	—	0	0.05	—	0.05	
		15	—	0.05	—	0	0.05	—	0.05	
	V _{OH}	5.0	4.95	—	4.95	5.0	—	4.95	—	Vdc
		10	9.95	—	9.95	10	—	9.95	—	
		15	14.95	—	14.95	15	—	14.95	—	
Input Voltage (V _O = 4.5 Vdc) (V _O = 9.0 Vdc) (V _O = 13.5 Vdc)	V _{IL}	5.0	—	1.0	—	2.25	1.0	—	1.0	Vdc
		10	—	2.0	—	4.50	2.0	—	2.0	
		15	—	2.5	—	6.75	2.5	—	2.5	
	V _{IH}	5.0	4.0	—	4.0	2.75	—	4.0	—	Vdc
		10	8.0	—	8.0	5.50	—	8.0	—	
		15	12.5	—	12.5	8.25	—	12.5	—	
Output Drive Current (V _{OH} = 2.5 Vdc) (V _{OH} = 4.6 Vdc) (V _{OH} = 9.5 Vdc) (V _{OH} = 13.5 Vdc)	Source I _{OH}	5.0	– 3.0	—	– 2.4	– 5.0	—	– 1.7	—	mAdc
		5.0	– 0.64	—	– 0.51	– 1.0	—	– 0.36	—	
		10	– 1.6	—	– 1.3	– 2.5	—	– 0.9	—	
		15	– 4.2	—	– 3.4	– 10	—	– 2.4	—	
	Sink I _{OL}	5.0	0.64	—	0.51	1.0	—	0.36	—	mAdc
		10	1.6	—	1.3	2.5	—	0.9	—	
		15	4.2	—	3.4	10	—	2.4	—	
Input Current	I _{in}	15	—	± 0.1	—	± 0.00001	± 0.1	—	± 1.0	μAdc
Input Capacitance (V _{in} = 0)	C _{in}	—	—	—	—	5.0	7.5	—	—	pF
Quiescent Current (Per Package)	I _{DD}	5.0	—	0.25	—	0.0005	0.25	—	7.5	μAdc
		10	—	0.5	—	0.0010	0.5	—	15	
		15	—	1.0	—	0.0015	1.0	—	30	
Total Supply Current (5.) (6.) (Dynamic plus Quiescent, Per Gate) (C _L = 50 pF)	I _T	5.0	I _T = (0.7 μA/kHz) f + I _{DD} /6 I _T = (1.4 μA/kHz) f + I _{DD} /6 I _T = (2.2 μA/kHz) f + I _{DD} /6							μAdc

4. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

5. The formulas given are for the typical characteristics only at 25°C.

6. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) Vfk$$

where: I_T is in μA (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.003.

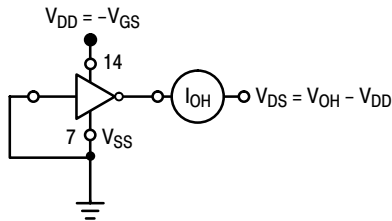
MC14007UB

SWITCHING CHARACTERISTICS (7.) ($C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$)

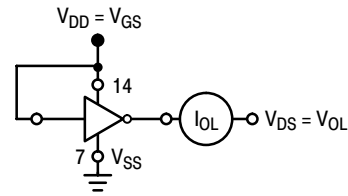
Characteristic	Symbol	V_{DD} Vdc	Min	Typ (8.)	Max	Unit
Output Rise Time $t_{TLH} = (1.2 \text{ ns/pF}) C_L + 30 \text{ ns}$ $t_{TLH} = (0.5 \text{ ns/pF}) C_L + 20 \text{ ns}$ $t_{TLH} = (0.4 \text{ ns/pF}) C_L + 15 \text{ ns}$	t_{TLH}	5.0 10 15	— — —	90 45 35	180 90 70	ns
Output Fall Time $t_{THL} = (1.2 \text{ ns/pF}) C_L + 15 \text{ ns}$ $t_{THL} = (0.5 \text{ ns/pF}) C_L + 15 \text{ ns}$ $t_{THL} = (0.4 \text{ ns/pF}) C_L + 10 \text{ ns}$	t_{THL}	5.0 10 15	— — —	75 40 30	150 80 60	ns
Turn-Off Delay Time $t_{PLH} = (1.5 \text{ ns/pF}) C_L + 35 \text{ ns}$ $t_{PLH} = (0.2 \text{ ns/pF}) C_L + 20 \text{ ns}$ $t_{PLH} = (0.15 \text{ ns/pF}) C_L + 17.5 \text{ ns}$	t_{PLH}	5.0 10 15	— — —	60 30 25	125 75 55	ns
Turn-On Delay Time $t_{PHL} = (1.0 \text{ ns/pF}) C_L + 10 \text{ ns}$ $t_{PHL} = (0.3 \text{ ns/pF}) C_L + 15 \text{ ns}$ $t_{PHL} = (0.2 \text{ ns/pF}) C_L + 15 \text{ ns}$	t_{PHL}	5.0 10 15	— — —	60 30 25	125 75 55	ns

7. The formulas given are for the typical characteristics only. Switching specifications are for device connected as an inverter.

8. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



All unused inputs connected to ground.



All unused inputs connected to ground.

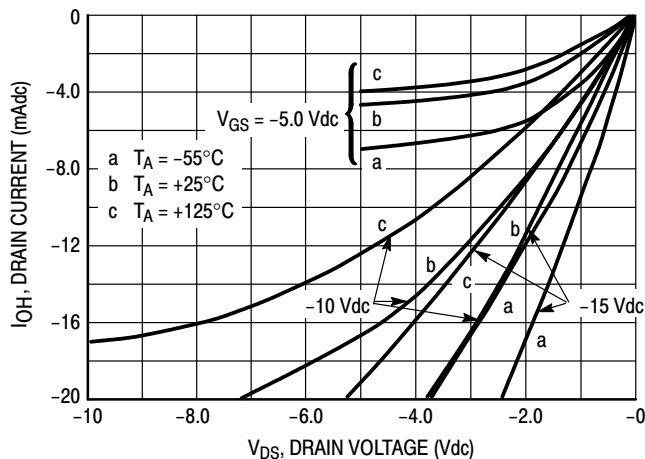


Figure 2. Typical Output Source Characteristics

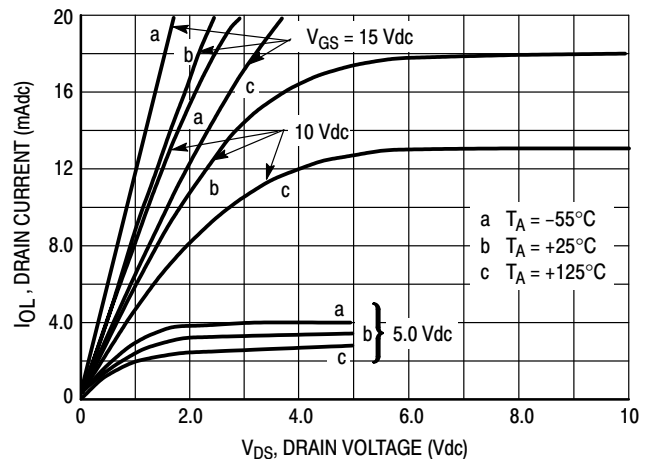


Figure 3. Typical Output Sink Characteristics

These typical curves are not guarantees, but are design aids.

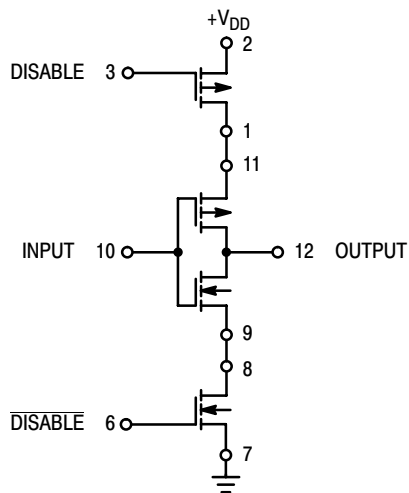
Caution: The maximum current rating is 10 mA per pin.



Figure 4. Switching Time and Power Dissipation Test Circuit and Waveforms

APPLICATIONS

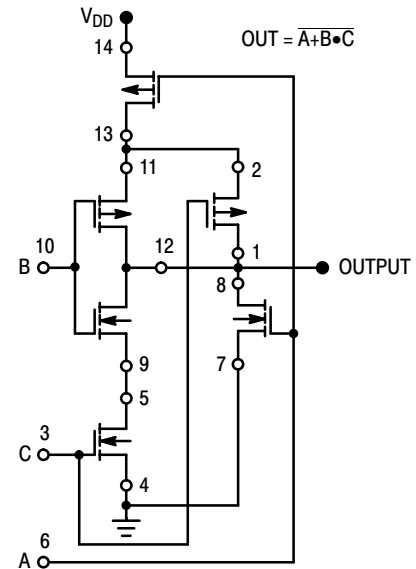
The MC14007UB dual pair plus inverter, which has access to all its elements offers a number of unique circuit applications. Figures 1, 5, and 6 are a few examples of the device flexibility.



INPUT	DISABLE	OUTPUT
1	0	0
0	0	1
X	1	OPEN

X = Don't Care

Figure 5. 3-State Buffer



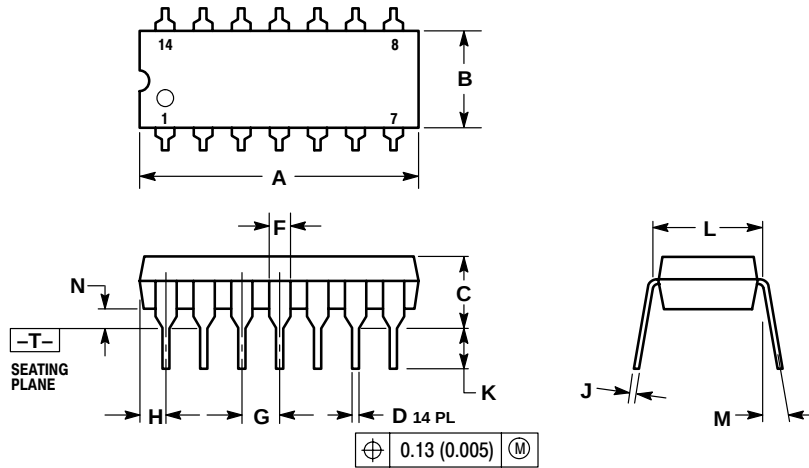
Substrates of P-channel devices internally connected to V_{DD} ;
Substrates of N-channel devices internally connected to V_{SS} .

Figure 6. AOI Functions Using Tree Logic

MC14007UB

PACKAGE DIMENSIONS

P SUFFIX PLASTIC DIP PACKAGE CASE 646-06 ISSUE M

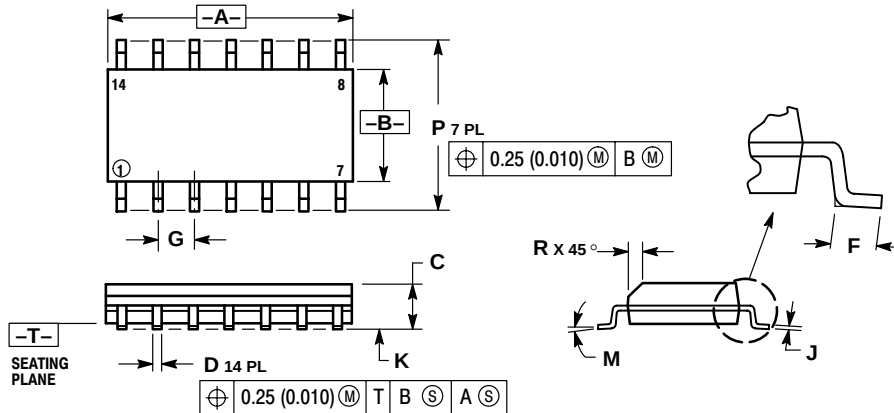


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	18.80
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M	---	10°	---	10°
N	0.015	0.039	0.38	1.01

D SUFFIX PLASTIC SOIC PACKAGE CASE 751A-03 ISSUE F



NOTES:

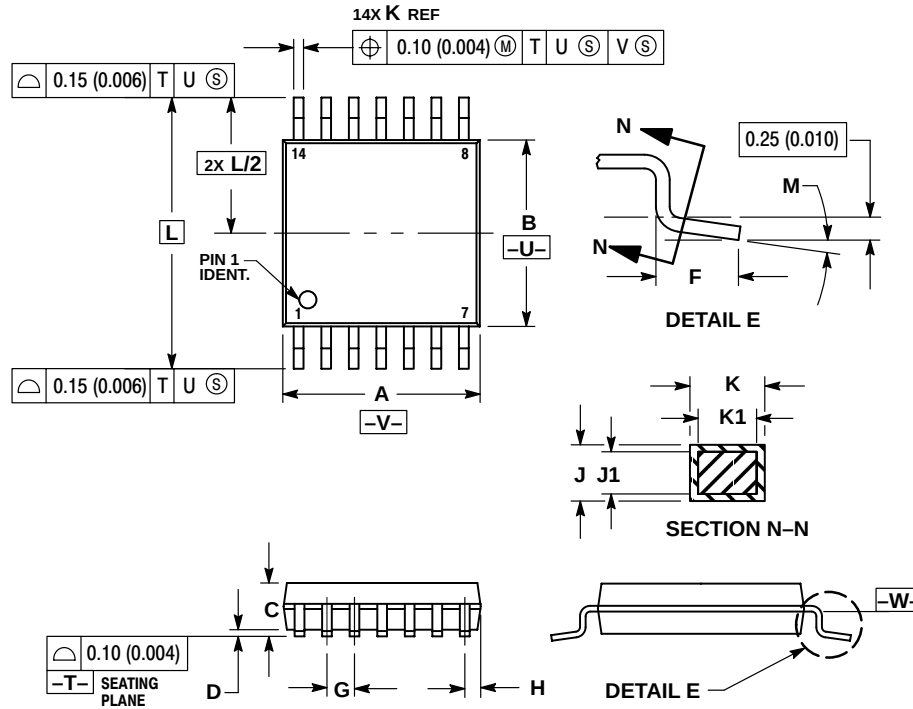
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.60	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

MC14007UB

PACKAGE DIMENSIONS

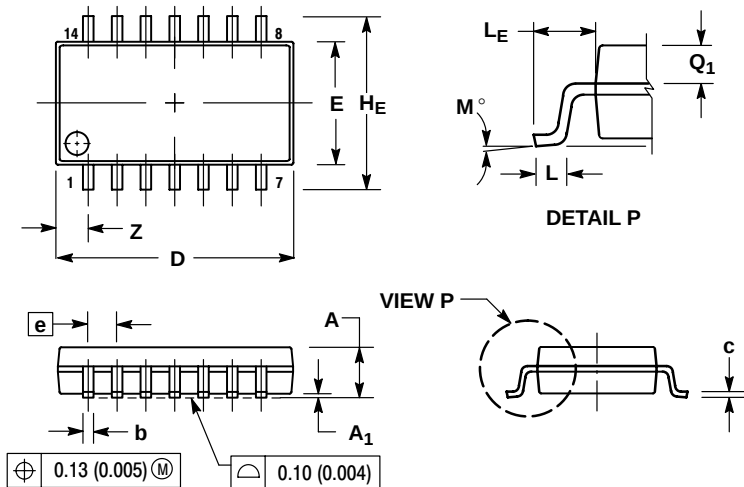
DT SUFFIX PLASTIC TSSOP PACKAGE CASE 948G-01 ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC	---	0.026 BSC	---
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC	---	0.252 BSC	---
M	0°	8°	0°	8°

F SUFFIX PLASTIC EIAJ SOIC PACKAGE CASE 965-01 ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC	---	0.050 BSC	---
H	7.40	8.20	0.291	0.323
H1	0.50	0.85	0.020	0.033
L	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q1	0.70	0.90	0.028	0.035
Z	---	1.42	---	0.056

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